

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

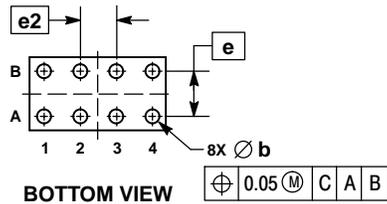
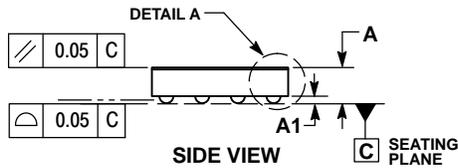
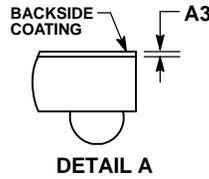
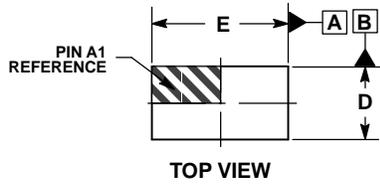
ON Semiconductor®



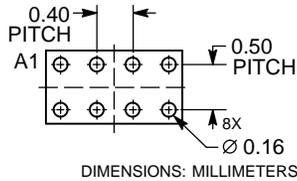
SCALE 4:1

WLCSP8 0.81x1.51x0.40
CASE 567UN
ISSUE O

DATE 02 JUN 2017



RECOMMENDED SOLDERING FOOTPRINT*



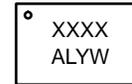
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.40
A1	0.05	0.08	0.11
A3	0.025 REF		
b	0.11	0.16	0.21
D	0.76	0.81	0.86
E	1.46	1.51	1.56
e	0.50 BSC		
e2	0.40 BSC		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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NEW STANDARD:		
DESCRIPTION:	WLCSP8 0.81X1.51X0.40	PAGE 1 OF 2

